

IEEE/CIC International Conference on Communications in China

IEEE/CIC ICC 2018

16-18 August 2018, Beijing, China

Conference Website: <http://iccc2018.ieee-iccc.org/>

IEEE/CIC International Conference on Communications in China (ICCC 2018) will be held in Beijing, China, 16-18 August, 2018. This conference will feature world-class plenary speakers, major technical symposia, industry and academic panels, tutorials and workshops. The technical program chairs invite the submission of original papers to following symposia for presentation and publication in the conference proceedings. Accepted and presented papers will be submitted to IEEE Xplore. Best paper awards will be selected from accepted papers.

Symposium of Next Generation Networking of IEEE/CIC ICC 2018

The Next-Generation Networking Symposium of IEEE ICC 2018 aims to provide a forum for researchers in both academia and industry to discuss the challenging research issues relevant to next generation networking technologies. To ensure complete coverage of the advances in this field, this symposium solicits original contributions in, but not limited to, the following topical areas:

- Future Internet Architecture and Design
- Next-Generation Access Networks
- Joint Access-Backhaul Network Design
- Moving Networks
- Software Defined Networking
- Information-Centric Networking, Peer-to-Peer Networking, and Social Networking
- Indoor Localization
- Data Center Networking, Network Virtualization and Services
- Network Convergence, Sustainability, and Resilience
- Privacy and Security Issues in NGN
- Network Planning and Management
- Network Service Provisioning, Measurement, and Management
- Interworking, Interconnection, Interoperability Issues of NGN
- Internet of Things (IoT), M2M, D2D, MTC
- Performance Evaluation
- Self-organization Networking

Submission Guidelines

The submitted papers should be original, not published or currently under review for

publications in any other journal or conference. All submissions must be formatted in standard IEEE camera-ready format and must be written in English and be at most six (6) printed pages in length, including figures. Papers should be submitted through EDAS System.

Important dates:

Paper Submission Deadline: 20 April, 2018

Acceptance Notification: 1 June, 2018

Camera-Ready: 15 June, 2018

Symposium Co-Chairs

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